



# BES2710IZC

Brief Datasheet

## Ultra-low Power Bluetooth Audio Platform for Headphones with Hybrid ANC

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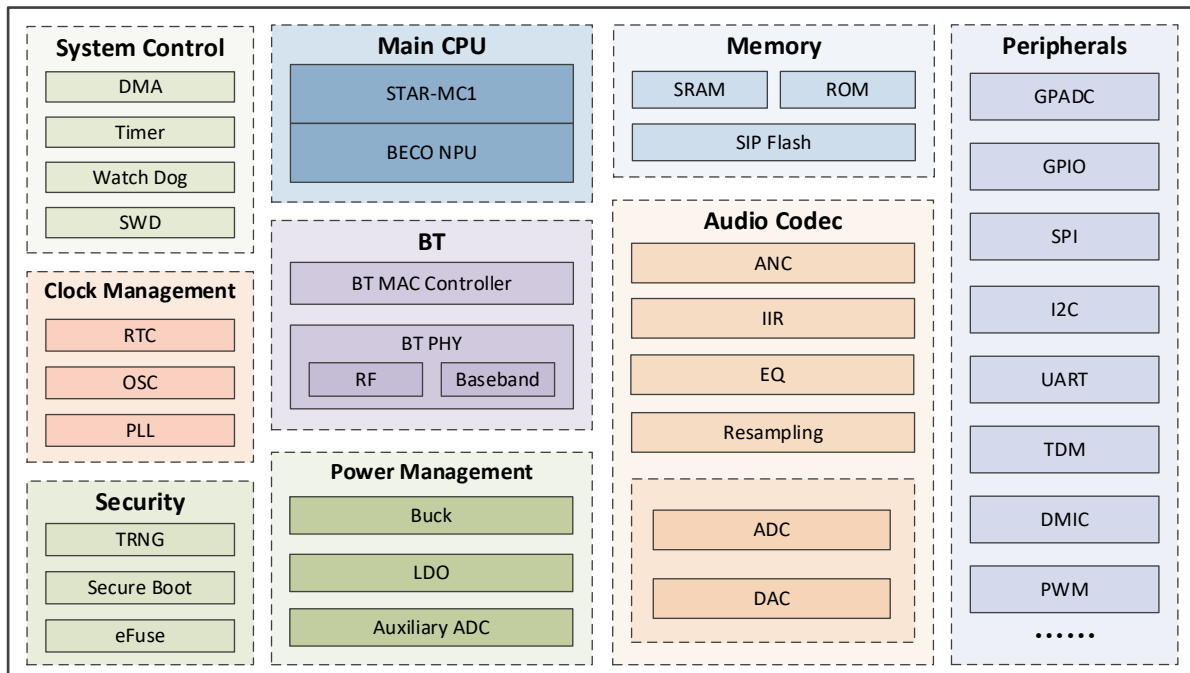
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## 1 General Description

The BES2710IZC is an ultra-low power, high performance Bluetooth audio SoC. The platform incorporates a CPU subsystem comprising a STAR-MC1 processor with a BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem with five high-quality ADCs and two DACs, ideal for headphone applications. The highly integrated design minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.



System Block Diagram

### 1.1 Applications

- Bluetooth headphones/headsets with hybrid ANC
- TWS earbuds with hybrid ANC
- Other portable audio devices

## 1.2 Features & Specifications\*

CPU Subsystem	STAR-MC1
Memory and Storage	Shared 864 KB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4
Audio & Voice Features	2x DACs
	5x ADCs
Peripheral Interfaces	GPADC/GPIO/SPI/I2C/UART/TDM/DMIC/PWM.....
Package	110-pin BGA

\* The content in the table is subject to change without notice.